

SOT989-1

plastic low profile fine-pitch ball grid array package; 401 balls; body 13 x 13 x 1 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA401
Package type industry code	LFBGA401
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	3-1-2007

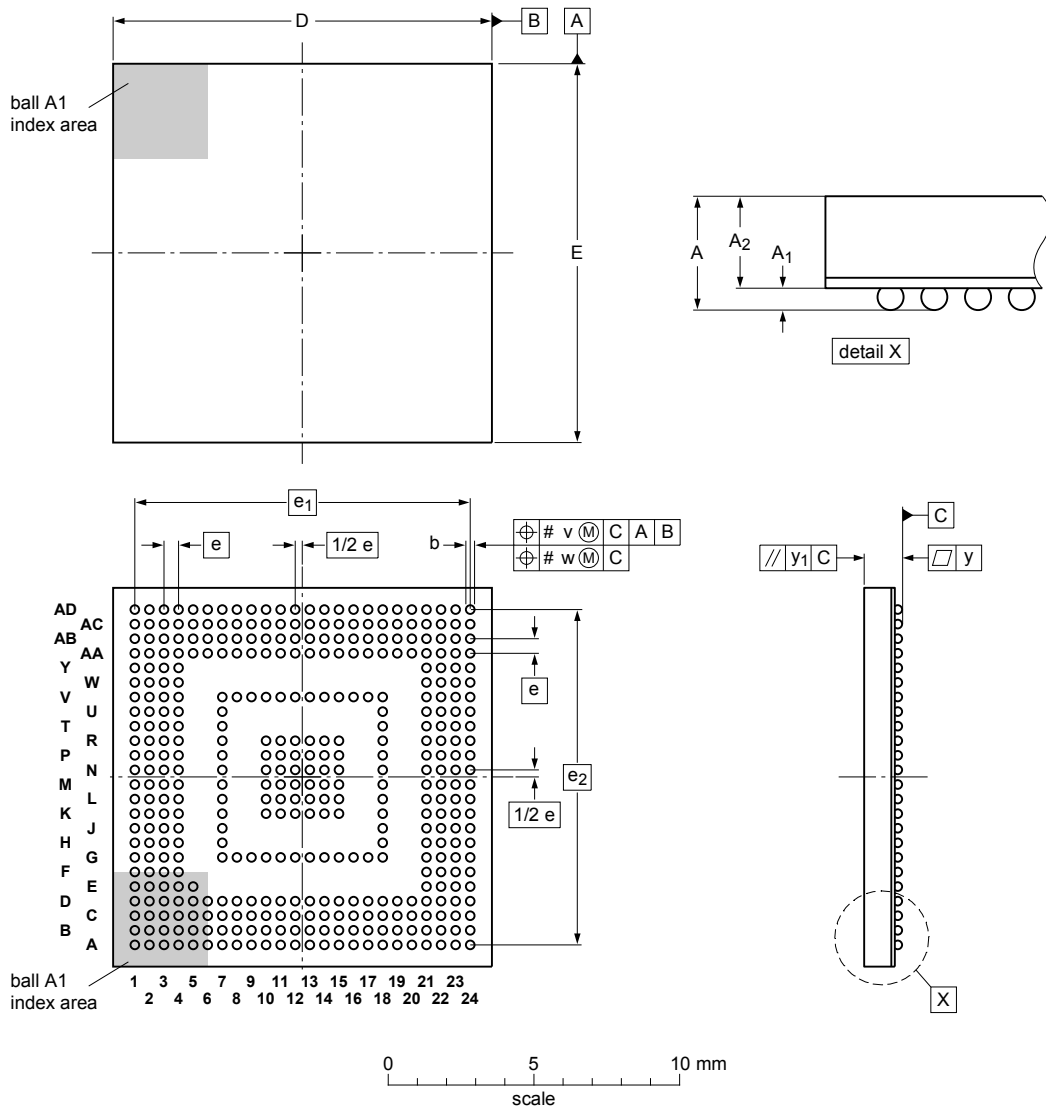
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	12.9	-	13	13.1	mm
E	package width	12.9	-	13	13.1	mm
A	seated height	[tbd]	-	1.4	1.4	mm
A ₂	package height	0.95	-	1	1.1	mm
n ₂	actual quantity of termination	-	-	401	-	



2. Package outline

LFBGA401: plastic low profile fine-pitch ball grid array package; 401 balls; body 13 x 13 x 1 mm SOT989-1



DIMENSIONS (mm are the original dimensions)

UNIT	A _{max}	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y	y ₁
mm	1.4	0.3 0.2	1.10 0.95	0.35 0.25	13.1 12.9	13.1 12.9	0.5	11.5	11.5	0.15	0.05	0.08	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT989-1		---				06-12-20 07-01-03

Fig. 1. Package outline LFBGA401 (SOT989-1)

3. Legal information

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For sales office addresses, please send an email to: salesaddresses@nxp.com
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